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**Erik Bodegom
Valérie Nguyen**
Editors

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Contents

vii Conference Committee

SESSION 1 COLOR AND MULTISPECTRAL TECHNIQUES

- 7249 02 **MonoColor CMOS sensor** [7249-01]
Y. P. Wang, Honeywell Scanning and Mobility (United States)
- 7249 03 **The implementation and spectrum response analysis of multifinger photogate APS pixels** [7249-03]
J. Leung, M. La Haye, G. H. Chapman, J. Liu, P. Kalyanam, M. Parameswaran, Simon Fraser Univ. (Canada)
- 7249 04 **Nanoplasmonic filters for image sensors** [7249-04]
S. Gétin, Y. Désières, M. Marie, G. Auvert, C. Pellé, O. Lartigue, L. Poupinet, L. Frey, CEA-LETI, Minatec (France)
- 7249 08 **Camera system for multispectral imaging of documents** [7249-09]
W. A. Christens-Barry, Equipoise Imaging, LLC (United States); K. Boydston, MegaVision, Inc. (United States); F. G. France, Library of Congress (United States); K. T. Knox, Boeing LTS, Inc. (United States); R. L. Easton, Jr., Rochester Institute of Technology (United States); M. B. Toth, R. B. Toth Associates (United States)

SESSION 2 SENSORS I

- 7249 09 **An ultra fast 100 ps, 100 μ m 3D pixel imager** [7249-10]
A. Kluge, CERN (Switzerland); G. Dellacasa, M. Fiorini, INFN Torino (Italy); P. Jarron, J. Kaplon, CERN (Switzerland); F. Marchetto, INFN Torino (Italy); E. Martin, CERN (Switzerland) and UCL Louvain la Neuve (Belgium); S. Martoiu, G. Mazza, INFN Torino (Italy); A. C. Ramusino, INFN Ferrara (Italy); P. Riedler, CERN (Switzerland); A. Rivetti, INFN Torino (Italy); S. Tiuraniemi, CERN (Switzerland)
- 7249 0B **Packaging and characterization of orthogonal transfer array CCDs for the WIYN One Degree Imager** [7249-12]
M. Lesser, D. Ouellette, G. Zareba, The Univ. of Arizona/Steward Observatory (United States); G. Jacoby, G. Muller, D. Sawyer, J. Keyes, WIYN Observatory (United States); R. Bredthauer, K. Boggs, Semiconductor Technology Associates Inc. (United States)
- 7249 0C **New 5.5 μ m interline transfer CCD platform for applied imaging markets** [7249-13]
D. A. Carpenter, J. A. DiBella, R. Kaser, S. L. Kosman, X. Liu, J. P. McCarten, E. J. Meisenzahl, D. N. Nichols, C. Parks, T. R. Pian, Eastman Kodak Co. (United States)

SESSION 3 SENSORS II

- 7249 0E **Low Gr/Gb sensitivity imbalance 3.2M CMOS image sensor with 2.2 μ m pixel** [7249-15]
N. Tanaka, J. Naruse, I. Inoue, H. Yamashita, M. Monoi, Toshiba Corp. (Japan)
- 7249 0F **16k pixel digital line-scan sensor with 12bit resolution and 40kS/second** [7249-16]
M. Wány, P. Franco, S. Voltz, AWAIBA Lda. (Portugal)
- 7249 0G **High-speed and high-dynamic range difference imaging based on the near-sensor image processing concept** [7249-17]
A. Åström, Combitech AB (Sweden); R. Forchheimer, Linköping Univ. (Sweden)

SESSION 4 NOVEL IMAGING DEVICES AND APPLICATIONS I

- 7249 0H **Experimental color video capturing equipment with three 33-megapixel CMOS image sensors** [7249-18]
T. Yamashita, NHK Science & Technical Research Labs. (Japan); S. Huang, Forza Silicon Corp. (United States); R. Funatsu, NHK Science & Technical Research Labs. (Japan); B. Mansoorian, Forza Silicon Corp. (United States); K. Mitani, Y. Nojiri, NHK Science & Technical Research Labs. (Japan)
- 7249 0I **A single-layer CCD image sensor with wide gap electrode and gradual potential channel** [7249-19]
M. Monoi, Toshiba Corp. (Japan); S. Sasaki, K. Dobashi, J. Iwai, H. Sekine, Iwate Toshiba Electronics (Japan); K. Tomita, Toshiba Corp. (Japan); M. Ooki, S. Mashiko, H. Saito, Toshiba Microelectronics (Japan); Y. Itabashi, Toshiba Corp. (Japan)
- 7249 0J **Low dark current, back-illuminated charge coupled devices** [7249-40]
R. C. Westhoff, B. E. Burke, H. R. Clark, A. H. Loomis, D. J. Young, J. A. Gregory, R. K. Reich, MIT Lincoln Lab. (United States)

SESSION 5 MODELING

- 7249 0L **Residual bulk image characterization and management in CCD image sensors** [7249-22]
R. D. Crisp, Tessera, Inc. (United States)
- 7249 0M **Characterization and system modeling of M-pixel CMOS arrays part II** [7249-23]
C. Tesdahl, P. Jain, D. Dorn, Pelco Corp. (United States)
- 7249 0N **Dark current behavior in DSLR cameras** [7249-24]
J. C. Dunlap, O. Sostin, R. Widenhorn, E. Bodegom, Portland State Univ. (United States)
- 7249 0O **Optimization of photodetector thickness in vertically-integrated image sensors** [7249-25]
O. Skorka, D. Sirbu, D. Joseph, Univ. of Alberta (Canada)

SESSION 6 NOVEL IMAGING DEVICES AND APPLICATIONS II

- 7249 OQ **Superconducting single photon detectors for ultrasensitive visible and IR detection** [7249-27]
R. Espiau de Lamaestre, CEA, LETI, MINATEC (France); L. Maingault, CEA, INAC, MINATEC (France); L. Frey, C. Constancias, CEA, LETI, MINATEC (France); P. Cavalier, J. C. Villégier, CEA, INAC, MINATEC (France); P. Odier, J. P. Poizat, Institut Néel, CNRS/UJF (France)
- 7249 OR **High quantum efficiency, back-illuminated, crystallographically etched, silicon-on-sapphire avalanche photodiode with very wide dynamic range, for manufacturable high resolution imaging arrays** [7249-28]
A. G. Stern, D. C. Cole, Boston Univ. (United States)
- 7249 OS **A day and night MOS imager spectrally adjusted for a wide range of color temperatures** [7249-29]
S. Koyama, K. Tanaka, M. Muguruma, M. Usuda, K. Fujiwara, T. Matsuno, Y. Hirose, Y. Shimada, Panasonic Corp. (Japan)
- 7249 OT **High-speed sequential image acquisition using a CMOS image sensor with a multi-lens optical system and its application for three-dimensional measurement** [7249-30]
D. Miyazaki, H. Shimizu, Osaka City Univ. (Japan); Y. Nakao, T. Toyoda, Y. Masaki, Funai Electric Co., Ltd. (Japan)
- 7249 OU **Fast single-photon imager acquires 1024 pixels at 100 kframe/s** [7249-31]
F. Guerrieri, Politecnico di Milano (Italy); S. Tisa, Micro Photon Devices (Italy); F. Zappa, Politecnico di Milano (Italy) and Micro Photon Devices (Italy)

SESSION 7 APPLICATIONS

- 7249 OV **Minimal form factor digital-image sensor for endoscopic applications** [7249-32]
M. Wány, S. Voltz, F. Gaspar, L. Chen, AWAIBA Lda. (Portugal)
- 7249 OW **Self-calibrating optical object tracking using Wii remotes** [7249-33]
I. F. Rickard, J. E. Davis, Univ. of California, Santa Cruz (United States)
- 7249 OX **Spectroscopy using the Hadamard Transform** [7249-34]
D. J. Fixsen, Univ. of Maryland (United States); M. A. Greenhouse, Goddard Space Flight Center (United States); J. W. MacKenty, Space Telescope Science Institute (United States); J. C. Mather, Goddard Space Flight Center (United States)

INTERACTIVE PAPER SESSION

- 7249 OY **Non-contact finger vein acquisition system using NIR laser** [7249-35]
J. Kim, H.-J. Kong, S. Park, S. Noh, S.-R. Lee, T. Kim, H. C. Kim, Seoul National Univ. (Korea, Republic of)
- 7249 OZ **A static multiplex Fabry-Perot spectrometer** [7249-37]
N. Zheng, N. Hagen, R. John, D. J. Brady, Duke Univ. (United States)

Author Index

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- 1 Color and Multispectral Techniques
Erik Bodegom, Portland State University (United States)
- 2 Sensors I
Valerie Nguyen, Commissariat à l'Energie Atomique (France)
- 3 Sensors II
Morley M. Blouke, Ball Aerospace & Technologies Corporation (United States)
- 4 Novel Imaging Devices and Applications I
Alice L. Reinheimer, e2v (United States)

- 5 Modeling
Morley M. Blouke, Ball Aerospace & Technologies Corporation (United States)
- 6 Novel Imaging Devices and Applications II
Valerie Nguyen, Commissariat à l'Energie Atomique (France)
- 7 Applications
Erik Bodegom, Portland State University (United States)